Yes No

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE DECLARATION FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled:

## A NEW PROCESS FOR PREPARATION OF IMIPENEM

the specification of which	h:		
_X is attached hereto;	or		
was filed on	, 20	05 as U.S. Application	Serial No.
I hereby state that I have specification, including t herein.			ne above identified any, specifically referred to
I acknowledge the duty in accordance with Title			t is material to patentability
	FOREIGN	PRIORITY CLAIM	
foreign application(s) for	r patent or inventor's cation for patent or in	s certificate listed below eventor's certificate have	s Code § 119(a)-(d) of any wand have also identified ving a filing date before tha
No such foreign app	olications have been f	iled	
X such foreign applica	tion have been filed	as follows:	
EARLIEST FOREIGN (6 MONTHS FOR DES			
Application Number	Country	Date of Filing	Priority Claimed Under 35 USC 119
10-2003-0088857	Korea	December 9 2003	X Yes No

					Dock	cet No	***
ALL FORE	ALL FOREIGN APPLICATION(S), IF ANY FILED MORE THAN 12 MONTHS (6 MONTHS FOR DESIGN) PRIOR TO THIS U.S. APPLICATION						
· A	pplication Nun	iber	Country		D	ate of Filing	
				•			1
							1
CL	AIM FOR B	ENEFIT <b>O</b> F	EARLIER U.S	S. PROVIS	IONAL A	APPLICATIO	NS
I hereby cla	im neigeity he	nefits under '	Title 35, Unite	d States C	nde 8110/	a) of any Uni	itad States
	patent application			u States Ct	oge 81 i s(	e), of any on	iteu States
no sı	u <b>ch</b> U.S. prov	risional applic	cations have be	een filed.			
such U.S. provisional application have been filed as follows:							
	Application	n Number	Date of F	iling		ty Claimed 35 USC 119	
					Y	cs No	
					Y	es No	
					Y	es No	
	CLAIM FOR BENEFIT OF EARLIER U.S./PCT APPLICATION(S)						
application application first paragr information Regulation	(s) listed below is not disclosurable of Title 3 that is mater s, §1.56 which	w and, insofased in the price of the price o	35, United States ar as the subject United States at Code, §11 ability in according to me be filing date of	et matter of es application. 2, I acknow dance with etween the	feach of ton in the rewledge the Title 37, filing date	he claims of the manner provide duty to disclarate Code of Fede	his led by the lose all ral
no suc	h U.S./PCT a	pplications h	ave been filed.				
such U.S./PCT application have been filed as follows:							
Applicat	tion Number	Relati	onship	Parent Application		Date of	Filing

Doc	ket No.	

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

I hereby appoint:

All practitioners at Customer Number 24998

all of Dickstein Shapiro Morin & Oshinsky LLP, 2101 L Street NW, Washington, DC 20037-1526, jointly, and each of them severally, my attorneys at law/patent agent(s), with full power of substitution, delegation and revocation, to prosecute this application, to make alterations and amendments therein, to receive the patent, and to transact all business in the U. S. Patent and Trademark Office connected therewith.

Please mail all correspondence to Thomas J. D' Amico, whose address is:

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Docket No.

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Third inventor's signature	Date
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Mailing Address	

Docket No.

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